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(71) Applicant: MINNESOTA MINING AND MANUFACTURING COMPANY [US/US]; 3M Center, P.O. Box 33427, Saint Paul, MN 55133-3427 (US).

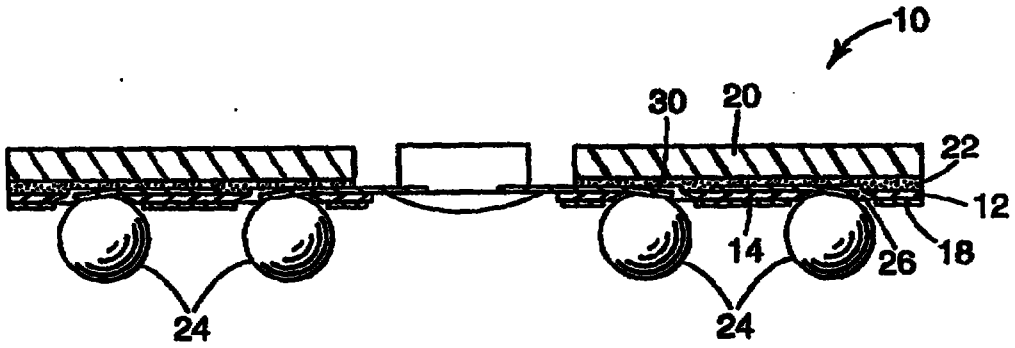
(72) Inventors: SCHUELLER, Randolph, D.; P.O. Box 33427, Saint Paul, MN 55133-3427 (US). WINDSCHITL, David, J.; P.O. Box 33427, Saint Paul, MN 55133-3427 (US).

(74) Agents: NEAVEILL, Darla, P. et al.; Minnesota Mining and Manufacturing Company, Office of Intellectual Property Counsel, P.O. Box 33427, Saint Paul, MN 55133-3427 (US).

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(54) Title: FLEXIBLE LEADS FOR TAPE BALL GRID ARRAY CIRCUIT



(57) Abstract

A flexible circuit construction includes a polymeric sheet, via holes in the sheet and metal circuitry disposed on the sheet. The circuitry terminates at a cantilever end partially spanning the via hole to which a solder ball is subsequently attached. The cantilever end allows the solder ball to move relative to the flexible circuit and thus compensate for misalignment and differential thermal expansion effects.